688072

2023

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www.sse.com.cn

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4.8 2024 3 31 188,188,255

191,540 187,996,715 90,238,423

278,426,678

2023

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A			688072	

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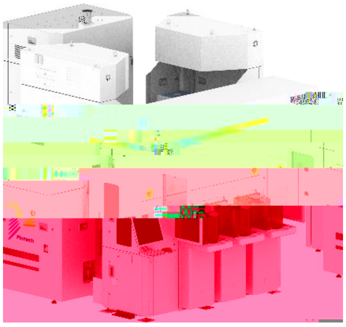
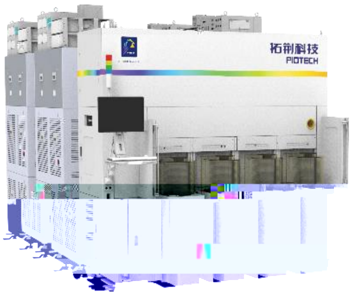
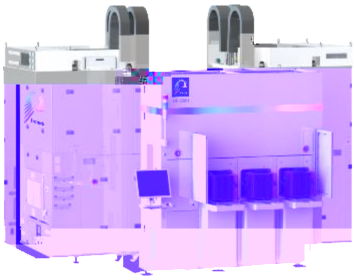
	900 024-24188000-8089	900 024-24188000-8089

PECVD ALD SACVD HDPCVD

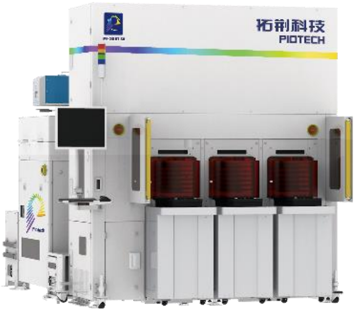
2

PF-300T pX PF-300T Plus pX		
PF-300T Supra-D PF-300M Supra-D		
NF-300H		Thick TEOS
PF-150T PF-200T		SiC SiO$_2$ SiN TEOS SiON

UV Cure

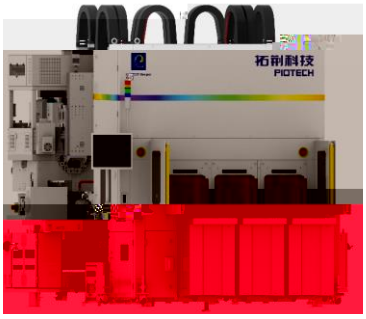
PF-300T Altair		Al_2O_3
TS-300 Altair		

3 SACVD

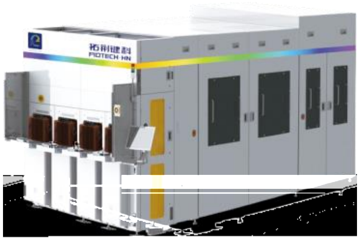
PF-300T SA		SA TEOS 8 12 SACVD
PF-300T SAF		

4 HDPCVD

PF-300T
Hesper



5

Dione 300		љ	12

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Demo Demo

5

Demo

( )

1.

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2022

SEMI 2023

1,063 1.3% 2023

2024 2025

1,240

2023 29% 366

SEMI 2023

90% 960

22% 2023

211 29%

2023 61

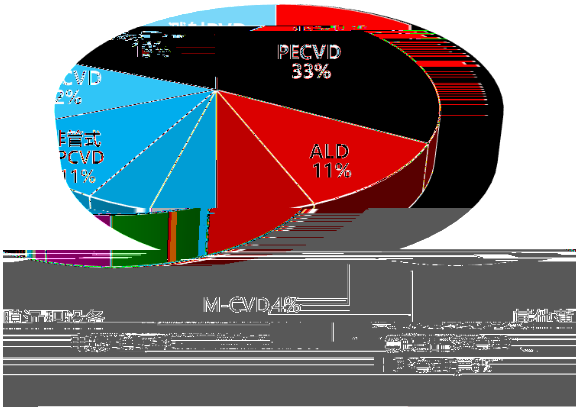
CVD PVD CVD PECVD

ALD SACVD HDPCVD

SEMI PECVD

33% ALD 11% SACVD HDPCVD

6%



SEMI

“ ”

Chiplet

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18-24

2.

Gartner CVD AMAT Lam

TEL 70%

EV Group SUSS TEL

PECVD ALD SACVD HDPCVD

PECVD ALD SACVD HDPCVD

3.

SEMI 300mm 2025 20% 1,165 2026

12% 1,305 4

300 WPM

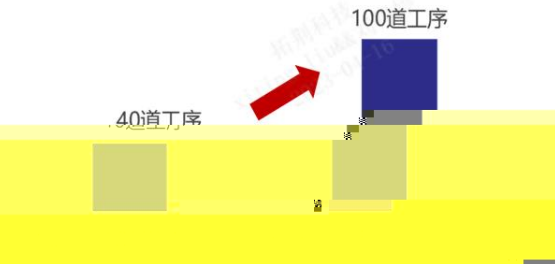
2023 5.5% 2,960 2024 6.4% 3,000

200mm 2024 18 2023

12% 760 2024 13% 860

90nm CMOS 40 FinFET

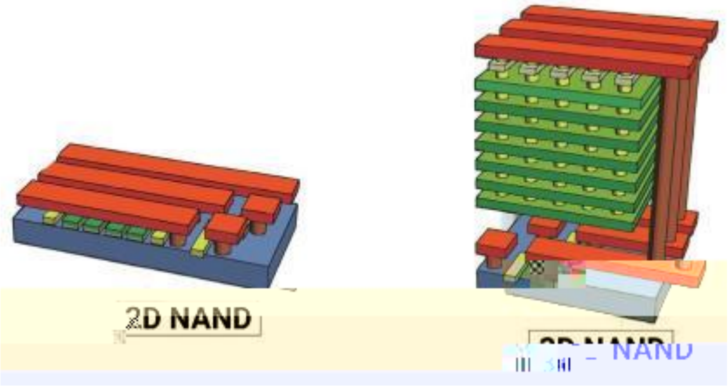
100 6 20



FLASH 2D NAND 3D NAND

3D NAND FLASH

2D NAND 3D NAND



SEMI

ALD

ALD

“ ”

Mirco Bump - Hybrid Bonding

AI

3

3.1 3

3.2

	1-3	4-6	7-9	10-12
	402,375,404.96	601,333,859.06	698,797,743.60	1,002,467,027.86
	53,718,794.24	70,847,159.09	146,452,704.36	391,565,178.40
	19,642,716.09	45,539,803.04	110,483,525.20	136,453,637.01
	-139,601,409.34	-603,227,746.16	-620,376,796.01	-294,136,701.26

□ √

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4.1 10

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( )	7,593
( )	9,495

			(%)				

	12,058,443	37,180,198	19.76	37,180,198			0	
	8,302,703	25,600,000	13.60	25,600,000				

2,303,775   2,303,775

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